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(54) **Title**: SOLID STATE LIGHTING DEVICES WITH REDUCED DIMENSIONS AND METHODS OF MANUFACTURING

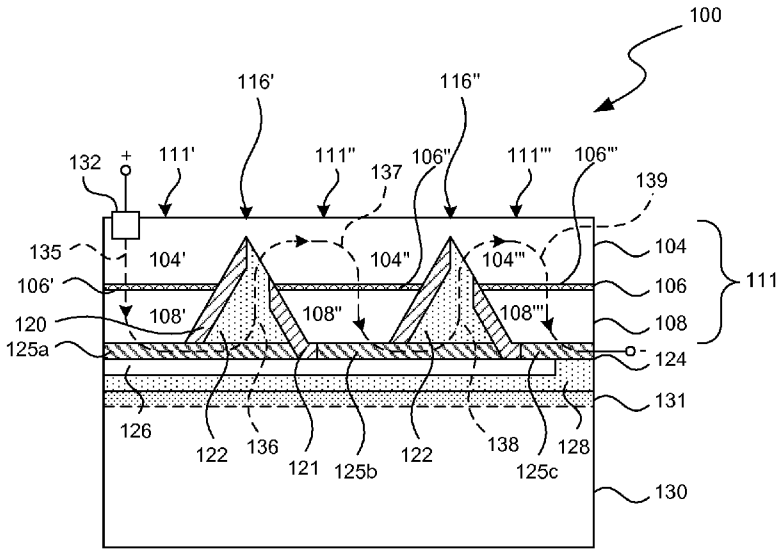


FIG. 3H

(57) **Abstract**: Solid state lighting (SSL) devices (e.g., devices with light emitting diodes) with reduced dimensions (e.g., thicknesses) and methods of manufacturing are disclosed herein. In one embodiment, an SSL device includes an SSL structure having a first region and a second region laterally spaced apart from the first region and an insulating material between and electrically isolating the first and second regions. The SSL device also includes a conductive material between the first and second regions and adjacent the insulating material to electrically couple the first and second regions in series.

WO 2012/102800 A1